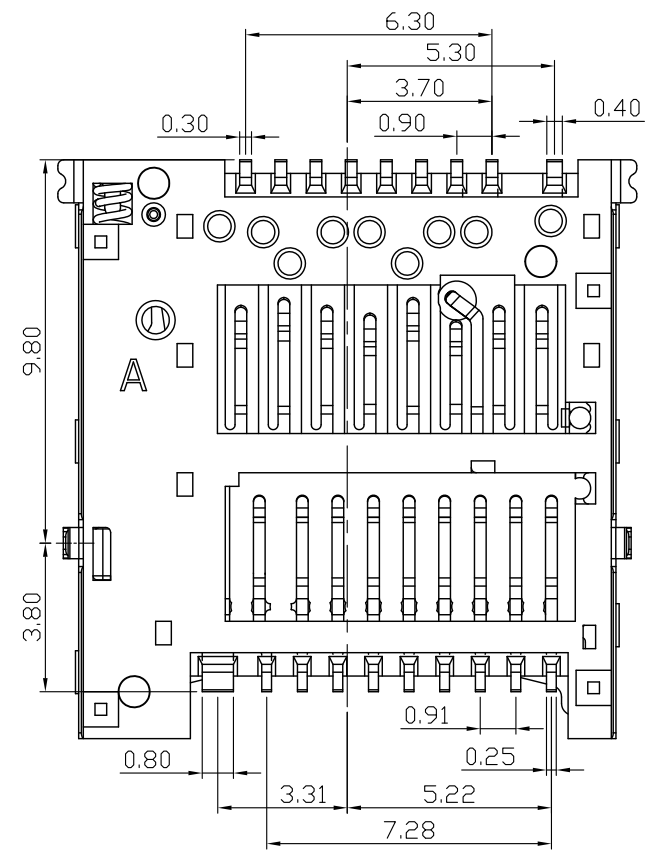
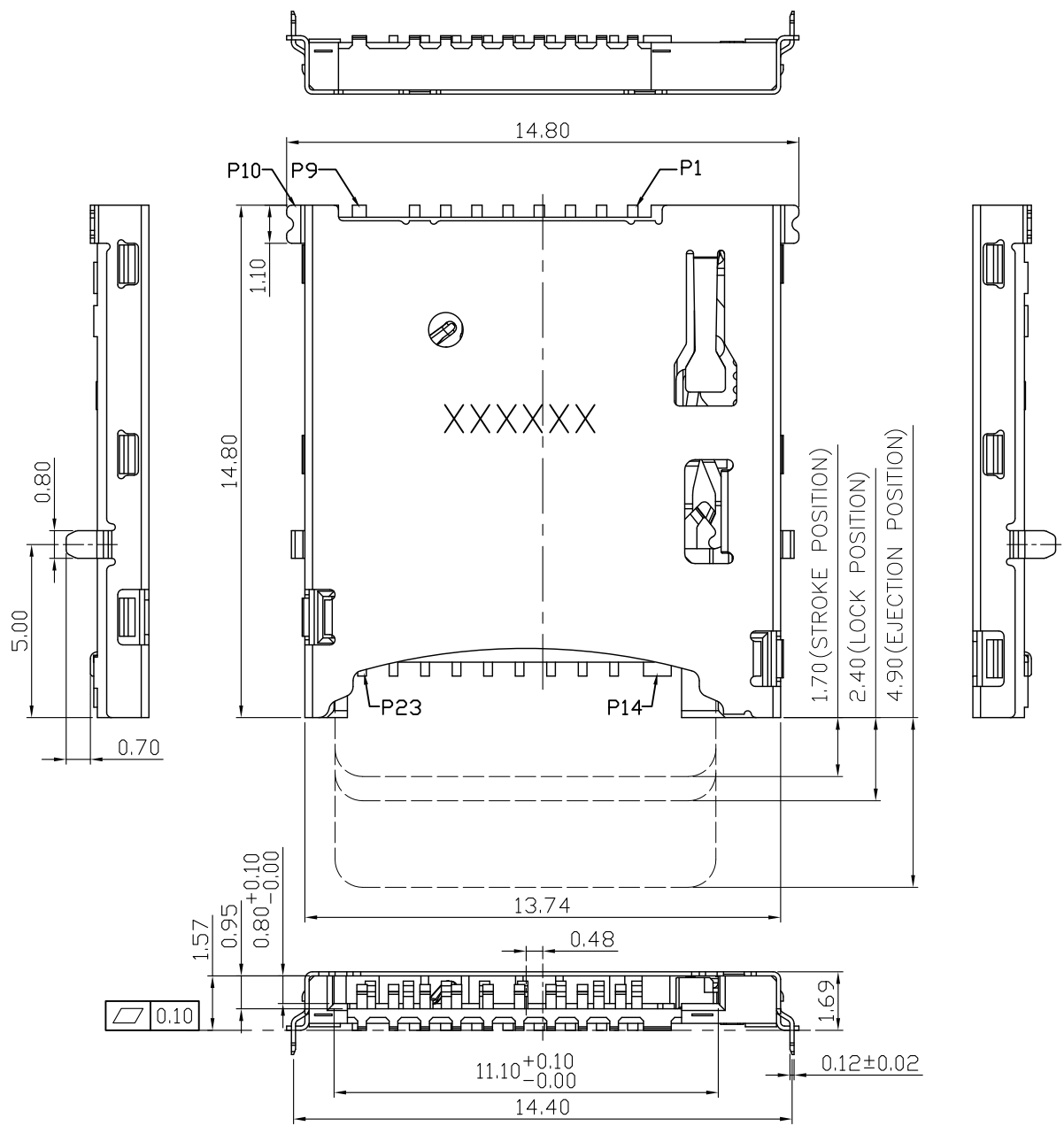


|      |         |                |
|------|---------|----------------|
| REV. | ECN.NO. | MODIFY.CONTENT |
|------|---------|----------------|

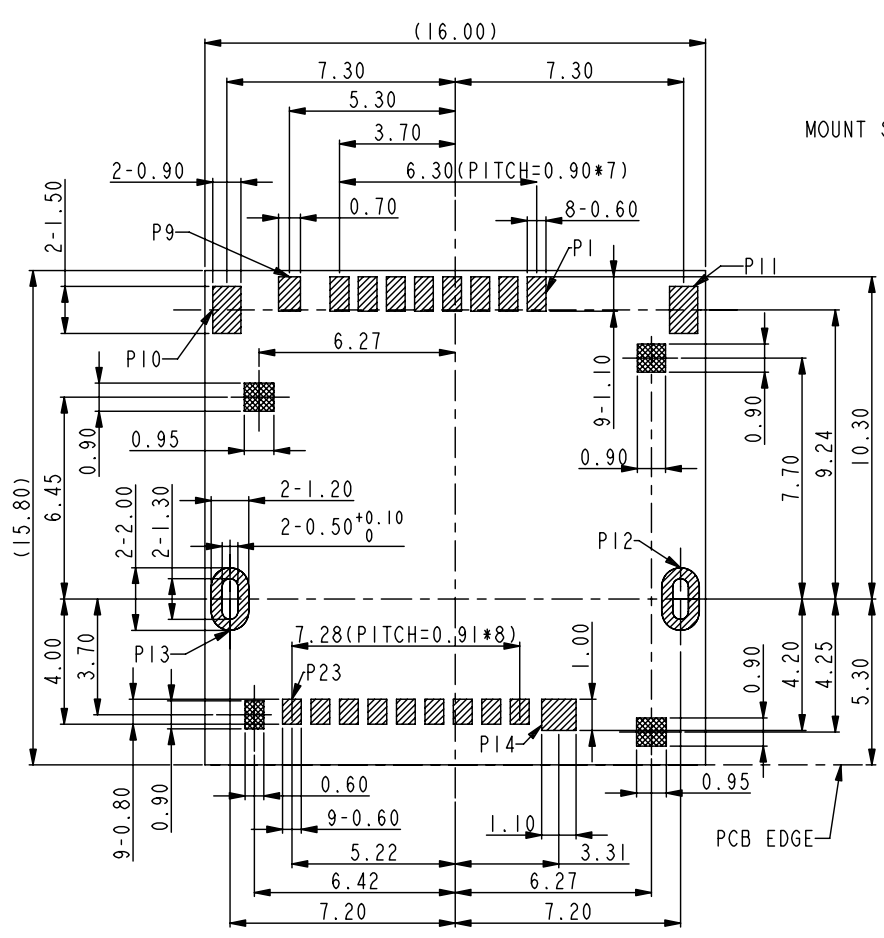


PART.NO.:  
MR213-AP401-\*\*

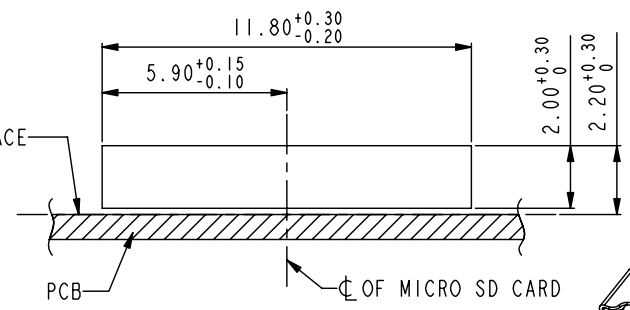
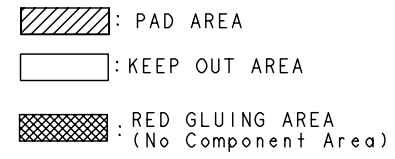
- 42: 功能区镀金10", 锡脚镀雾纯锡至少1000"
- 43: 功能区镀金30", 锡脚镀雾纯锡至少1000"
- 44: 功能区镀金50", 锡脚镀雾纯锡至少1000"
- 45: 功能区镀金100", 锡脚镀雾纯锡至少1000"
- 46: 功能区镀金150", 锡脚镀雾纯锡至少1000"
- 47: 功能区镀金300", 锡脚镀雾纯锡至少1000"

|                   |         |                |          |                             |          |                  |
|-------------------|---------|----------------|----------|-----------------------------|----------|------------------|
| GENERAL TOLERANCE | DWG.NO. | MR213-AP401-00 | PART.NO. | MR213-AP401-**              | DRAWN    | L.M.J 2020.04.15 |
| x.±0.50           | REV.    | A              | TITLE    | Micro SD4.0 Push H1.67 conn | CHECKED  |                  |
| .x±0.25           | SIZE    |                | SHEET    | 1/3                         | APPROVED |                  |
| .xx±0.15          | A4      |                |          |                             |          |                  |
| x.±5°             |         |                |          |                             |          |                  |
| x.±2°             |         |                |          |                             |          |                  |
| .xx±1°            |         |                |          |                             |          |                  |

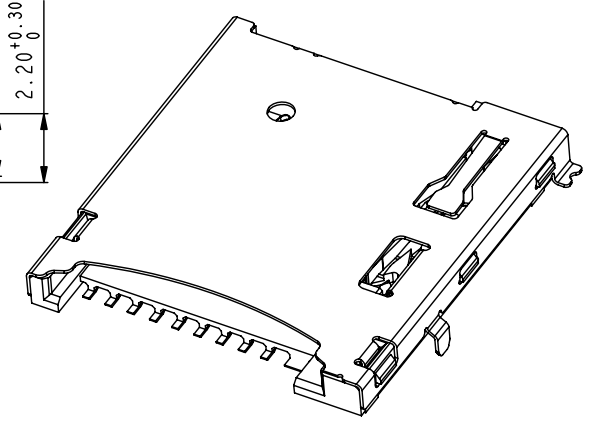
|   |    |       |     |
|---|----|-------|-----|
| UNIT  | mm | SCALE | 1:1 |
| <b>东莞市欧联电子科技有限公司</b><br>DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD. |    |       |     |



RECOMMENDED P.C.B LAYOUT  
TOP VIEW (TOLERANCE +/- 0.05)



RECOMMEND ID DIMENSION



PIN ASSIGNMENT

| Pin No. | Pin Assignment      |
|---------|---------------------|
| P1      | MICRO SD DAT2       |
| P2      | MICRO SD CD/DAT3    |
| P3      | MICRO SD CMD        |
| P4      | MICRO SD VDD1       |
| P5      | MICRO SD CLK        |
| P6      | MICRO SD VSS        |
| P7      | MICRO SD DAT0/RCLK+ |
| P8      | MICRO SD DAT1/RCLK- |
| P9      | MICRO SD CD         |
| P10     | GND                 |
| P11     | GND                 |
| P12     | GND                 |
| P13     | GND                 |
| P14     | GND                 |
| P15     | MICRO SD VDD2       |
| P16     | MICRO SD SWIO       |
| P17     | MICRO SD VSS        |
| P18     | MICRO SD D0+        |
| P19     | MICRO SD D0-        |
| P20     | MICRO SD VSS        |
| P21     | MICRO SD DI-        |
| P22     | MICRO SD DI+        |
| P23     | MICRO SD VSS        |

NOTES :

- MATERIAL :
  - HOUSING: LCP S475 UL94 V-0, BLACK COLOR.
  - SHELL: Stainless Steel SUS304.
  - CONTACT: Copper Alloy C5210.
- FINISH :
  - CONTACT: GOLD PLATING ON CONTACT AREA, MATTE TIN 100u" MIN ON SOLDER TAIL AREA. 50u" MIN NICKEL PLATING OVERALL.
  - SHELL: 30u" MIN NICKEL PLATING OVERALL. Au 1u" MIN ON SOLDER TAIL AREA.
- Electrical Characteristics:
  - Operating voltage : 100V AC(rms)/DC.
  - Current rating : 0.5 A.
  - Operating Temperature: -25°C ~ +85°C.
  - Contact resistance: 100 m ohms max.
  - Insulation resistance: 1000M ohms min. at 250VDC.
  - Dielectric withstanding voltage: 500 VAC/1minute.

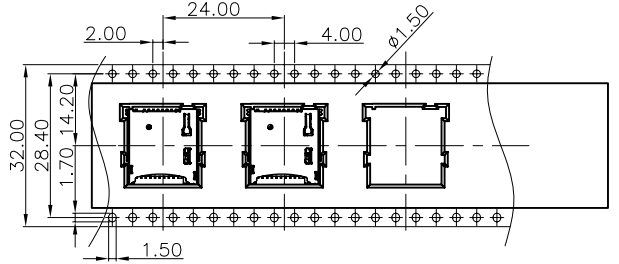
|                   |         |                             |                  |      |    |       |     |
|-------------------|---------|-----------------------------|------------------|------|----|-------|-----|
| GENERAL TOLERANCE | DWG.NO. | PART.NO.                    | DRAWN            | UNIT | mm | SCALE | 1:1 |
| x.±0.50           | REV.    | MR213-AP401-00              | L.M.J 2020.04.15 |      |    |       |     |
| .x±0.25           | SIZE    | MR213-AP401-**              | CHECKED          |      |    |       |     |
| .xx±0.15          | A4      | Micro SD4.0 Push H1.67 conn | APPROVED         |      |    |       |     |
|                   |         | SHEET                       | 2/3              |      |    |       |     |

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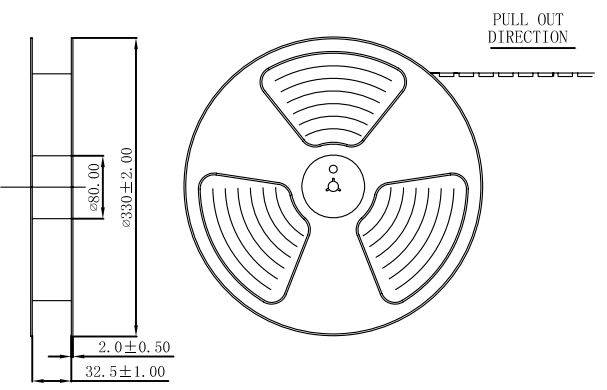
## 包装作业规范

### 包装作业图示及说明 (PACKING OPERATION DIAGRAM & INSTRUCTION)

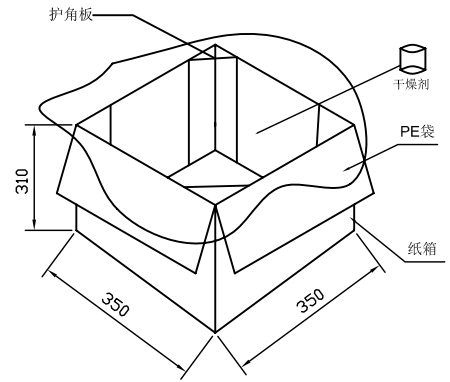
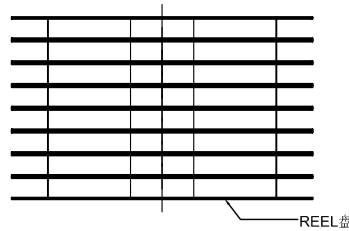
- 一.
- 1) 将成品一一放入REEL包装盘内, 依同一方向放入 .
  - 2) 包装时, 如下图所示 .
  - 3) 一个REEL包装盘放置600个成品 .



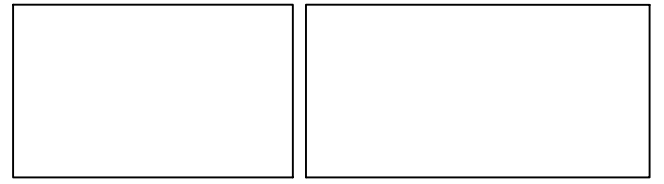
- 二.
- 1) 装盘前先把前面空15格, 然后再开始装盘, 尾端也需空出15格, 上带加长200mm.
  - 2) 装满成品的REEL包装盘如下图所示.



- 三.
- 1) 每箱装 8 盘REEL包装盘 .
  - 2) 每箱放置 4800 PCS 的成品 .



- 四.
- 1) 用TAPE将纸箱封实 .



#### 備註 (REMARK)

1. 若有未装满之零数箱, 必须以缓冲材塞满 .

|                   |                |                             |                  |
|-------------------|----------------|-----------------------------|------------------|
| GENERAL TOLERANCE | DWG.NO.        | PART.NO.                    | DRAWN            |
| x.±0.50           | MR213-AP401-00 | MR213-AP401-**              | L.M.J 2020.04.15 |
| x.±0.25           | REV.           | TITLE                       | CHECKED          |
| .xx±0.15          | A              | Micro SD4.0 Push H1.67 conn |                  |
|                   | SIZE           | SHEET                       | APPROVED         |
|                   | A4             | 3/3                         |                  |

|   |    |       |     |
|---|----|-------|-----|
| UNIT  | mm | SCALE | 1:1 |
| <b>东莞市欧联电子科技有限公司</b><br>DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD. |    |       |     |